

Progress on R&D at INFN-Pisa

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on behalf of the INFN Pisa mechanical studies group

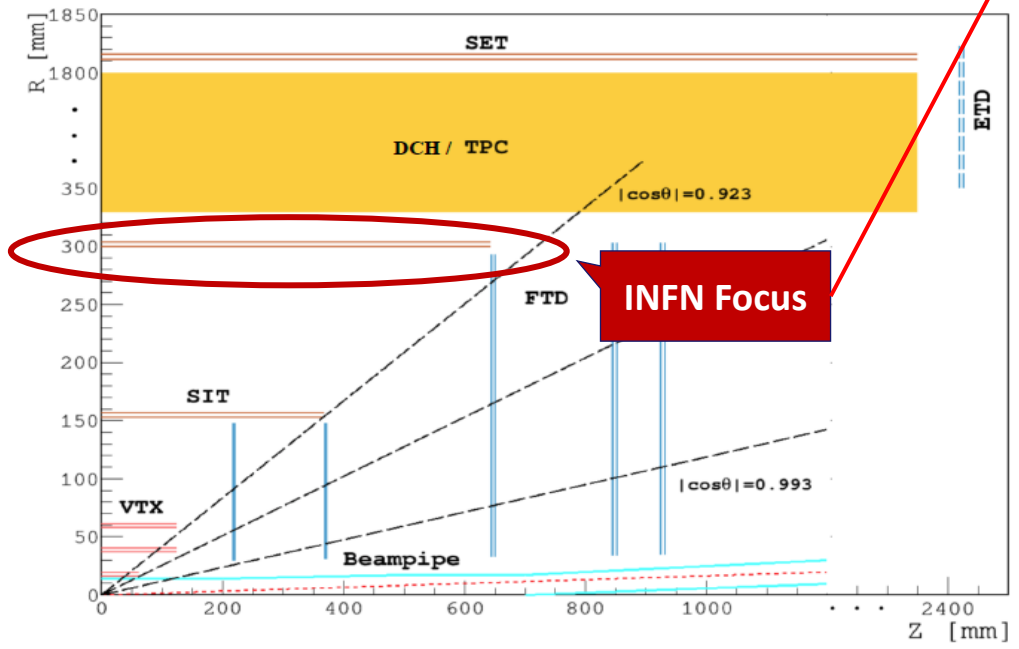


This project has received funding from the European Union's Horizon 2020 research and innovation programme under grant agreement No 101004761.

- Light structure for CEPC
- Light structure for Belle 2 DMAPS VTX Upgrade
- Conclusions

CepC Tracker

Baseline tracker design: TPC
 and 3 layers / 5 disks of silicon sensors,
 50 m² (33 w/o ETD) if built in CMOS pixels (strips default)



Detector		Radius R [mm]	$\pm z$ [mm]	Material budget [X_0]	
SIT	Layer 1	153	371.3	0.65%	
	Layer 2	300	664.9	0.65%	
SET	Layer 3	1811	2350	0.65%	
		R_{in}	R_{out}		
FTD	Disk 1	39	151.9	220	0.50%
	Disk 2	49.6	151.9	371.3	0.50%
	Disk 3	70.1	298.9	644.9	0.65%
	Disk 4	79.3	309	846	0.65%
	Disk 5	92.7	309	1057.5	0.65%
ETD	Disk	419.3	1822.7	2420	0.65%

Physics process	Measurands	Detector subsystem	Performance requirement
$ZH, Z \rightarrow e^+e^-, \mu^+\mu^-$	$m_H, \sigma(ZH)$	Tracker	$\Delta(1/p_T) = 2 \times 10^{-5} \oplus \frac{0.001}{p(\text{GeV}) \sin^{3/2}\theta}$
$H \rightarrow \mu^+\mu^-$	$BR(H \rightarrow \mu^+\mu^-)$		

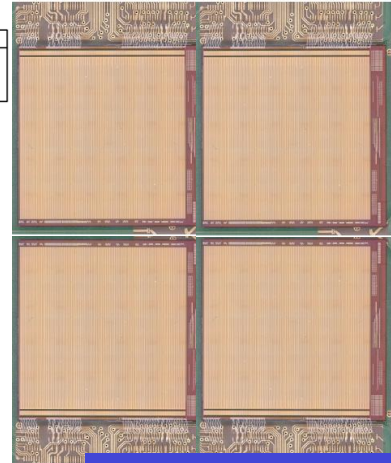
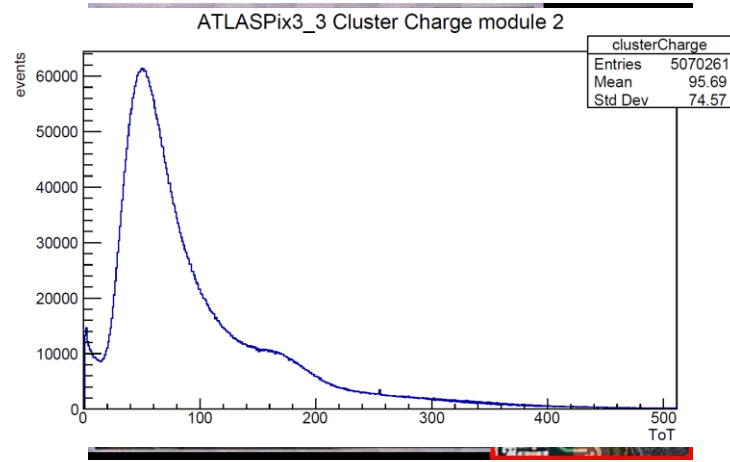
$$\sigma_{r\phi} \approx 7\mu\text{m}$$

AtlasPix3

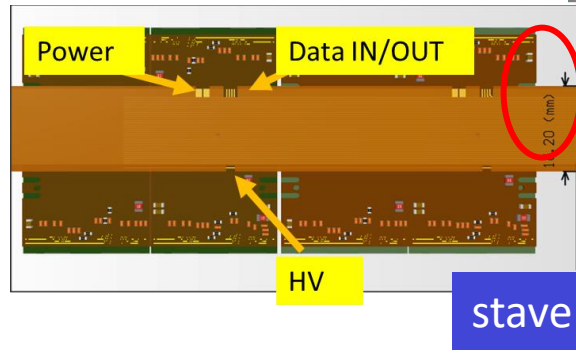
DETECTOR

Total thickness 372 μm
Total copper 36 μm

- Based on ATLASPIX3 R&D
 - 50 x 150 μm^2
 - Up to 1.28 Gb/s downlink
 - TSI 180 nm process
 - 132 columns of 372 pixels
- Active length (r-phi x z)
 - 18.6 mm x 19.8 mm
- Module is made of 2x2 chips
- Power goal 100 mW/cm² (175 now)
- Module tested on beam (DESY)



4 chip module



Attilio Andreazza Group
INFN Milano

Collaboration: INFN, IHEP, KIT, Liverpool

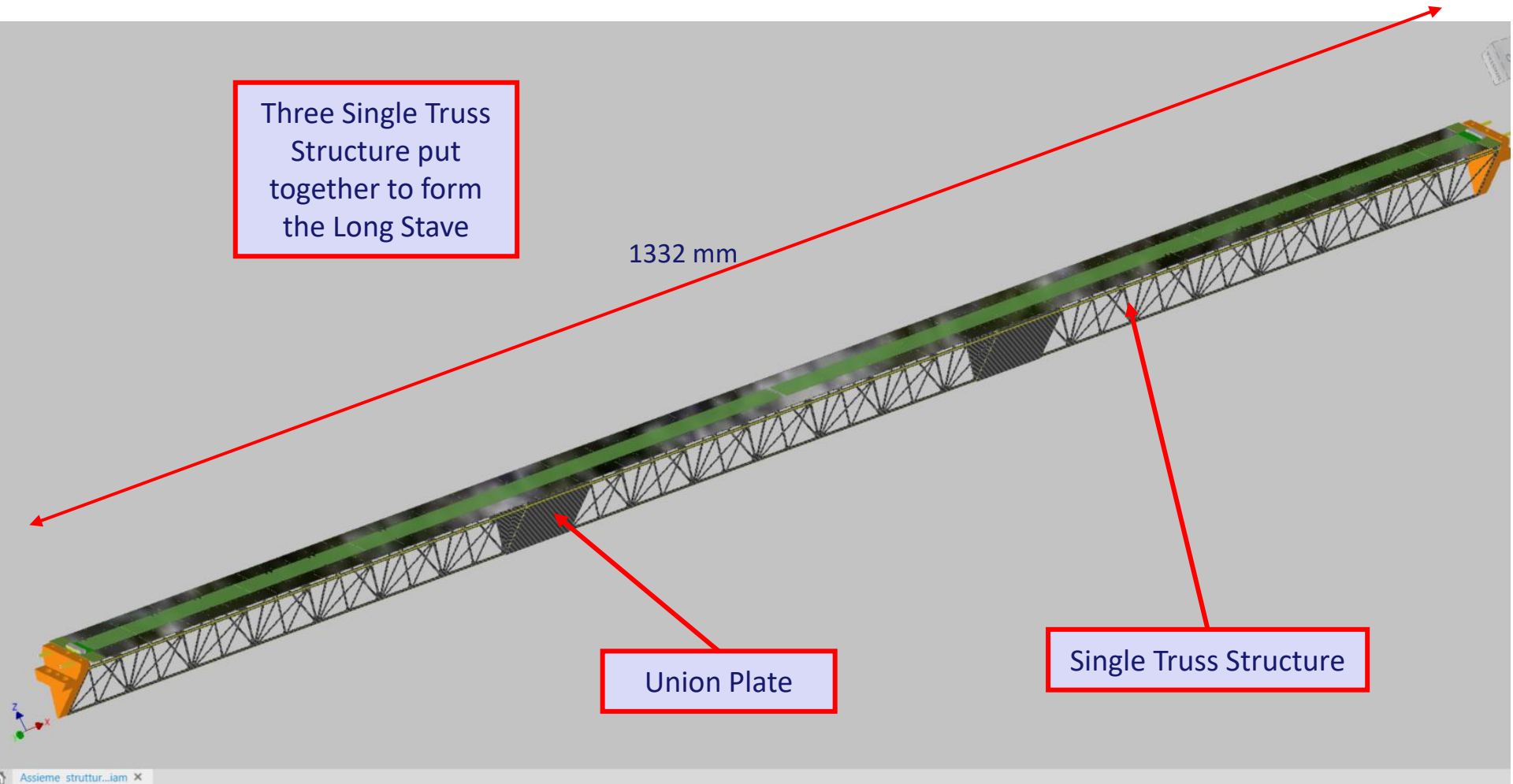
Long Stave for the Outer Tracker of the CEPC Experiment

Three Single Truss Structure put together to form the Long Stave

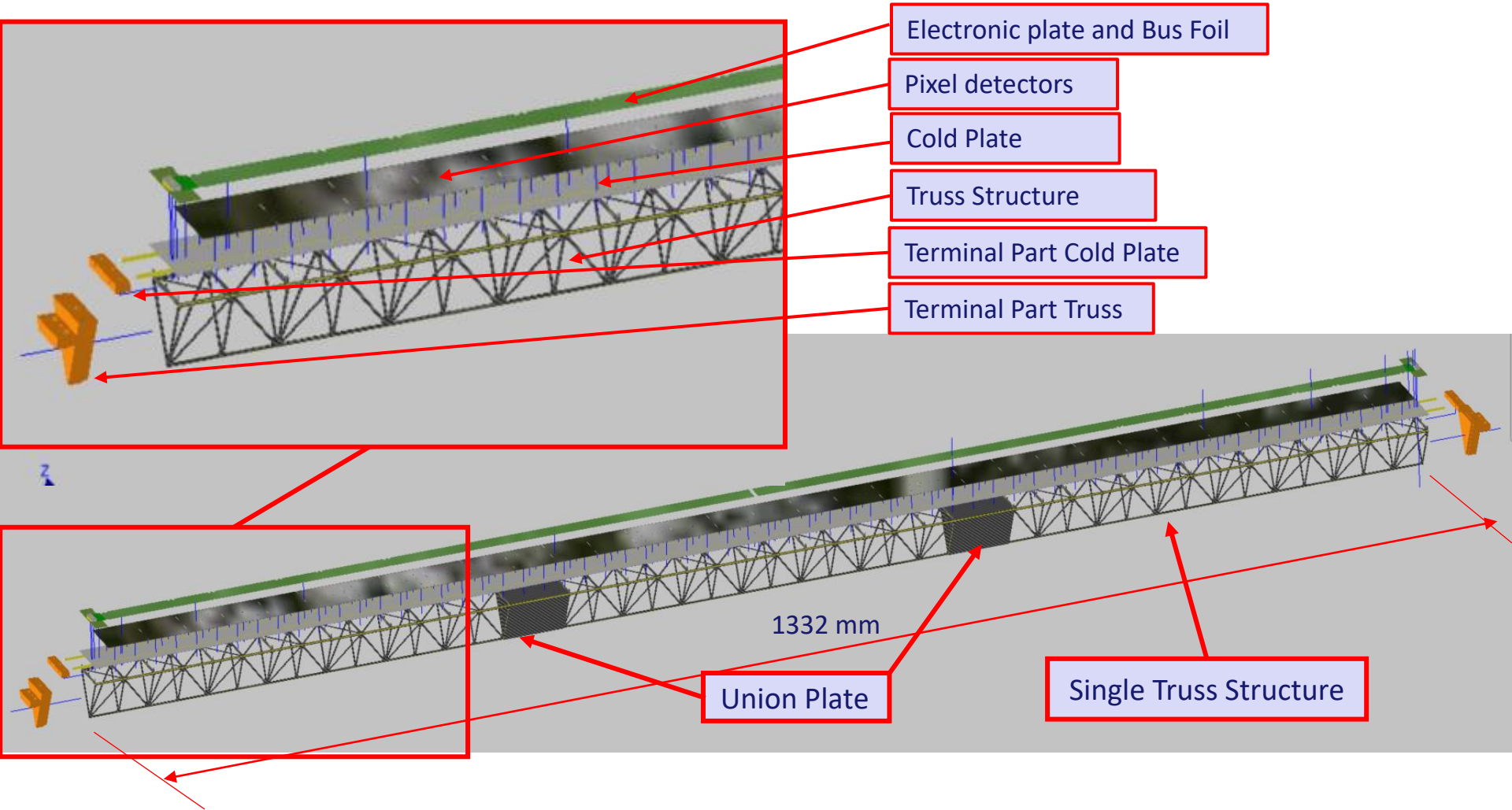
1332 mm

Union Plate

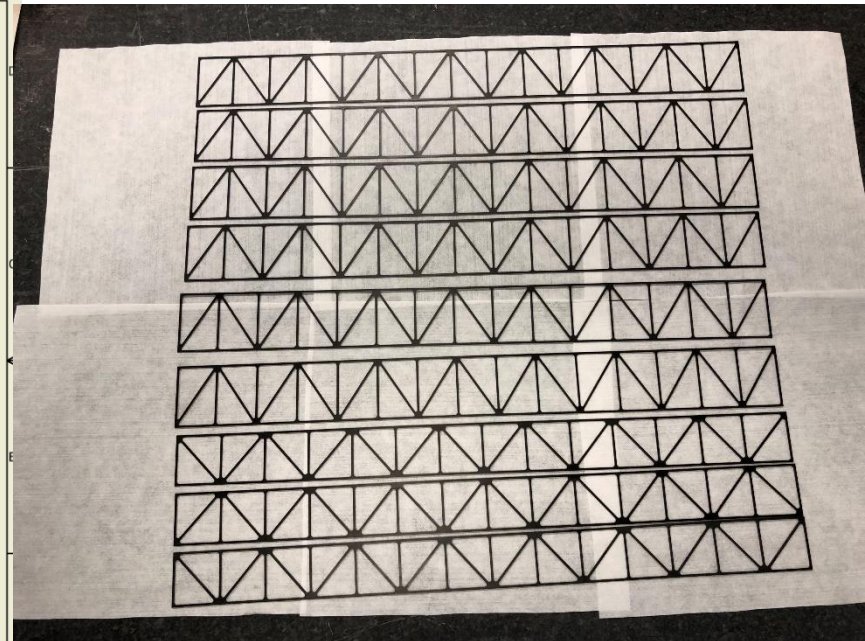
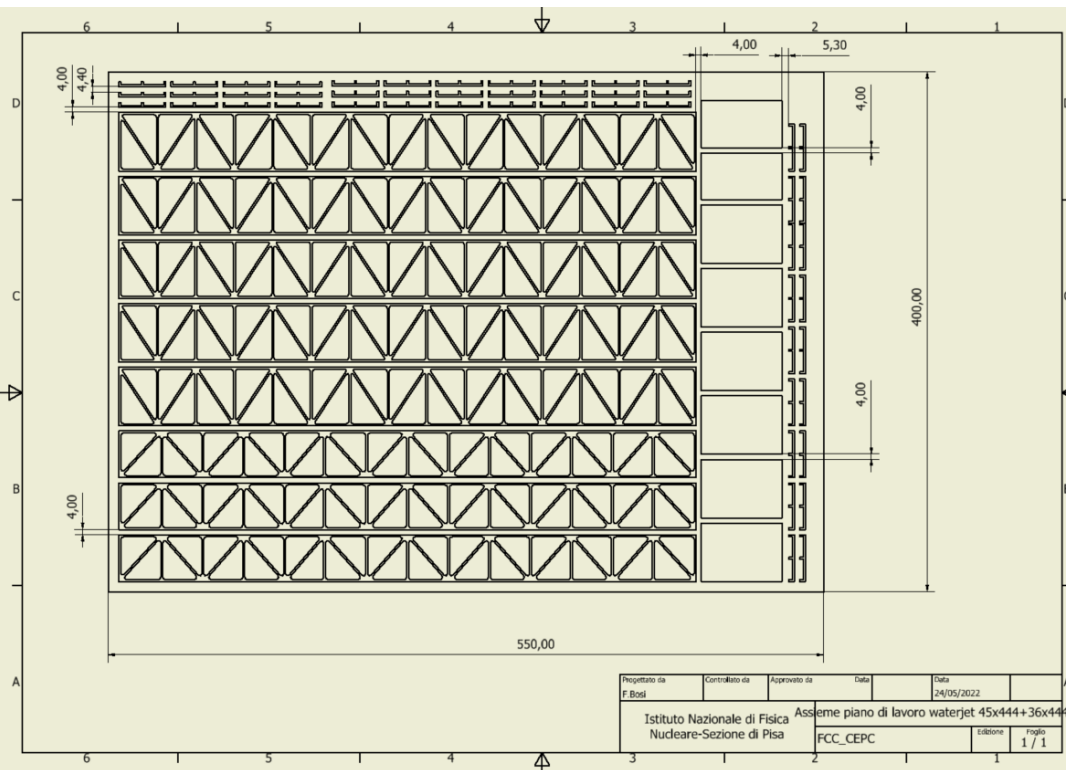
Single Truss Structure



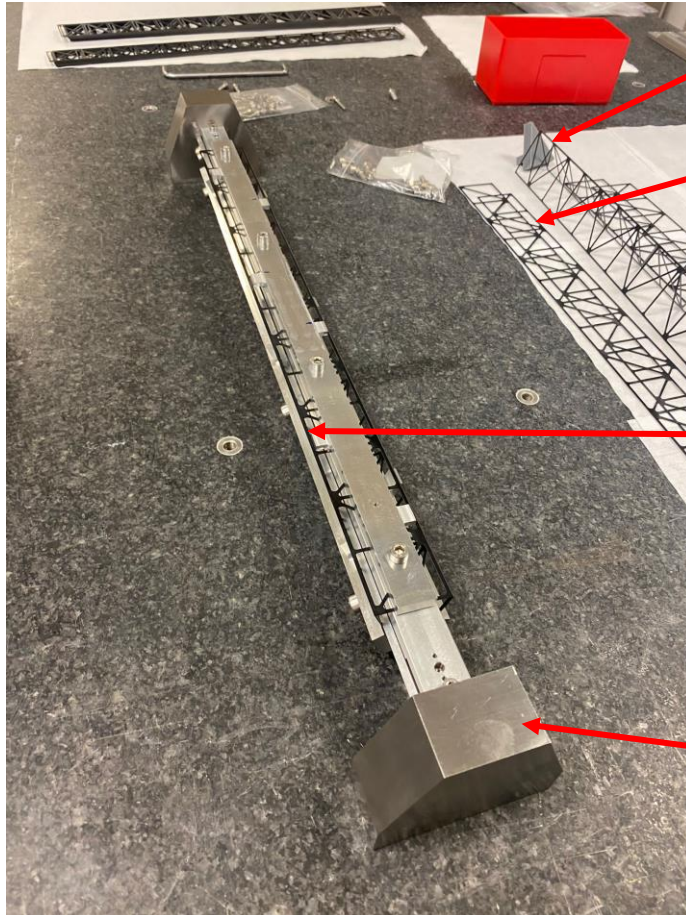
Long Stave Exploded View



- LAMINATED FOIL
- Th=0.5 mm of 550x460 mm²
- Carbon Fiber MJ46



Single truss structure realized by WataJet Company
Special process waterjet technology (precision 50 μm)



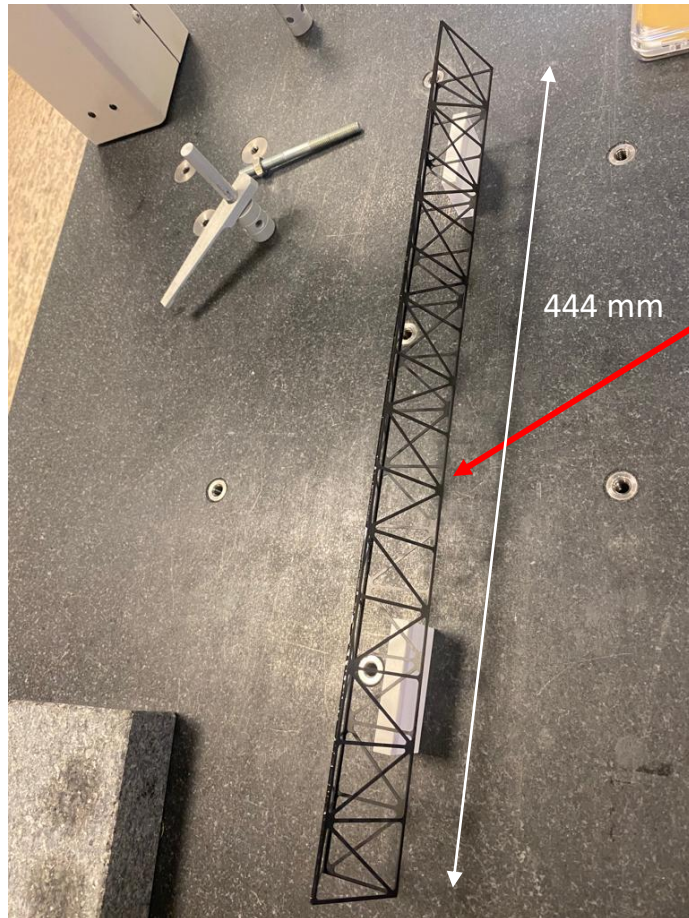
End piece truss structure

Single truss structure

Single truss structure mask assembled and glued on the mask

Short Mask

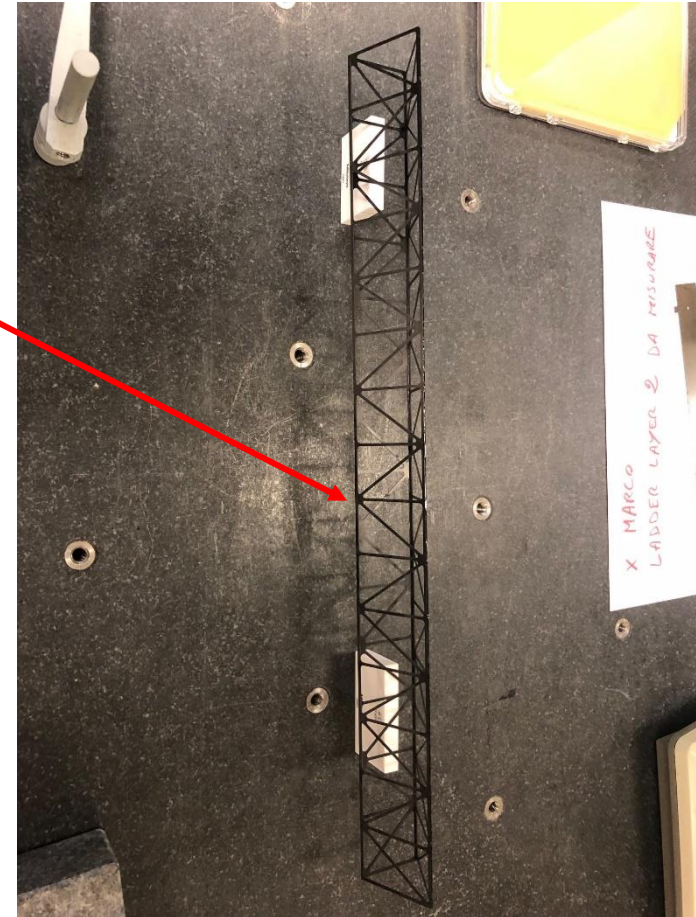
Single truss structure mask assembled and glued on the mask

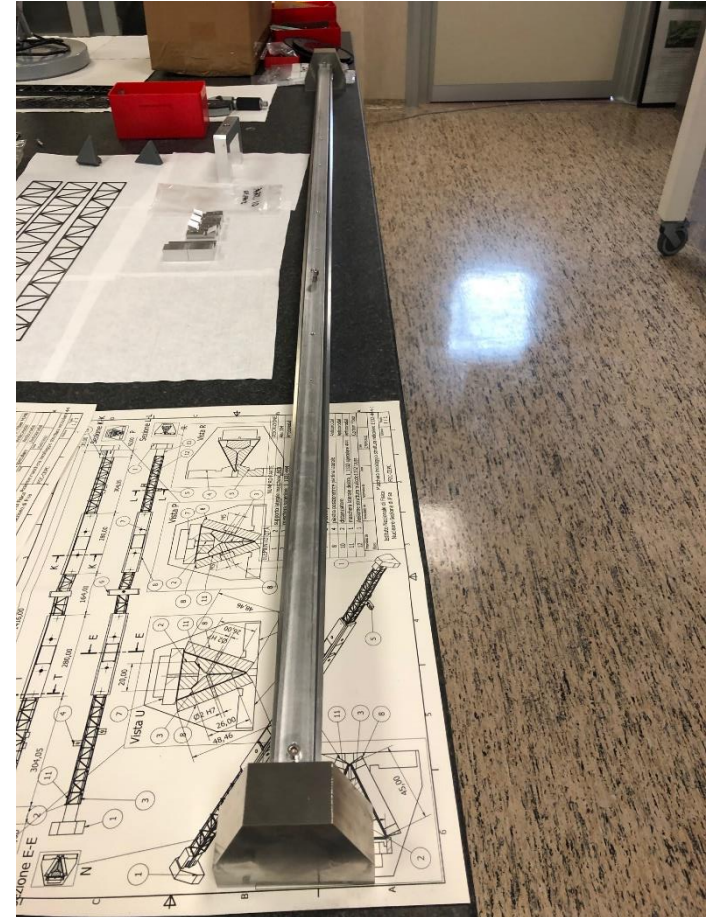
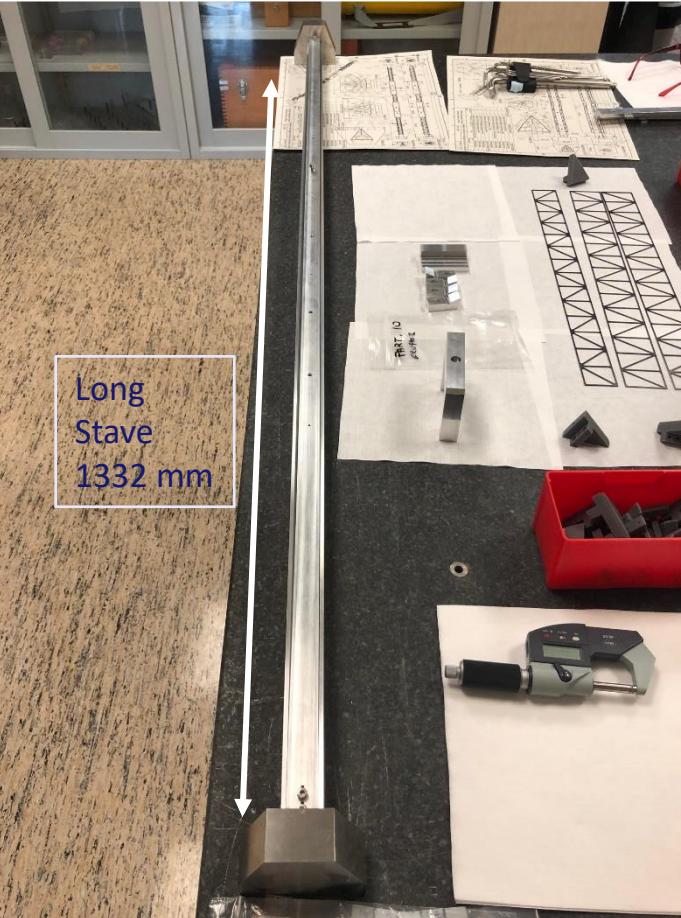


Single truss structure realized

glueing with Araldite 2011 and Cyanacrilate

Until now three truss structures realized

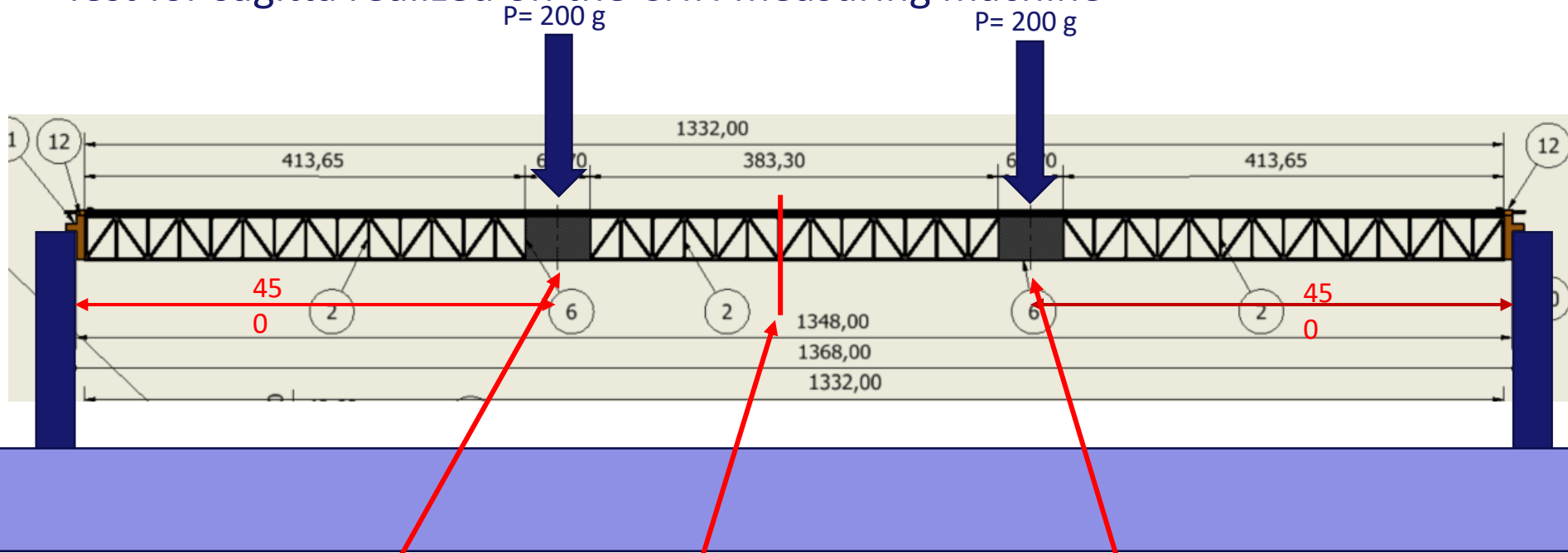




- One sample realized until now

EXPERIMENTAL TEST FOR THE SAGITTA VALUE OF SUPER WEIGHT LOAD

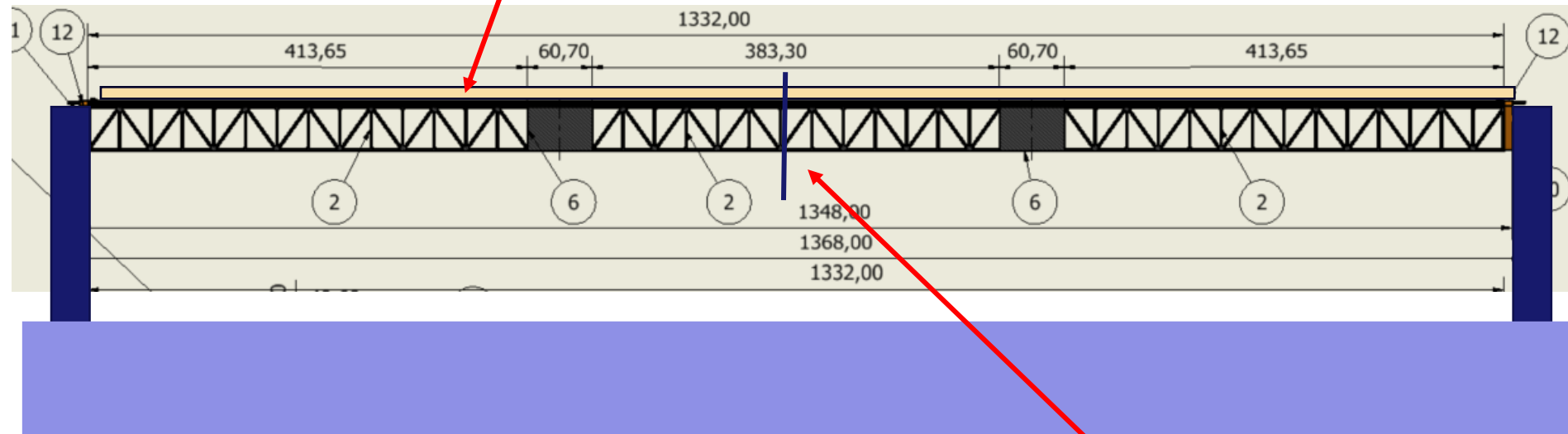
- Test for sagitta realized on the CNN measuring machine



Sagitta measured at the center and at the point where applied the load

EXPERIMENTAL TEST FOR THE SAGITTA VALUE OF THE REAL WEIGHT

Equivalent weight uniformly distributed of the detector + electronic + Power Bus + Cold Plate= 164,85 g



Test for sagitta realized on the CNN measuring machine

Sagitta measured at the center of the truss



- Truss Structure positioned under the 3D CNN Measuring Machine Hexagon DEA GIBLI
- Volume measured $3500 \times 1500 \times 1800 \text{ mm}^3$
- Precision X,Y,Z axis 4,5 micron

Super Weight Test

- Concentrated load 200 g at 450 mm from each edge
- Sagitta at 450 mm from the edge = 800micron
- Sagitta at the center of the structure = 900 micron

(Some difference with the simulation value attributable to a non conformal CFRP material: to be optimized)

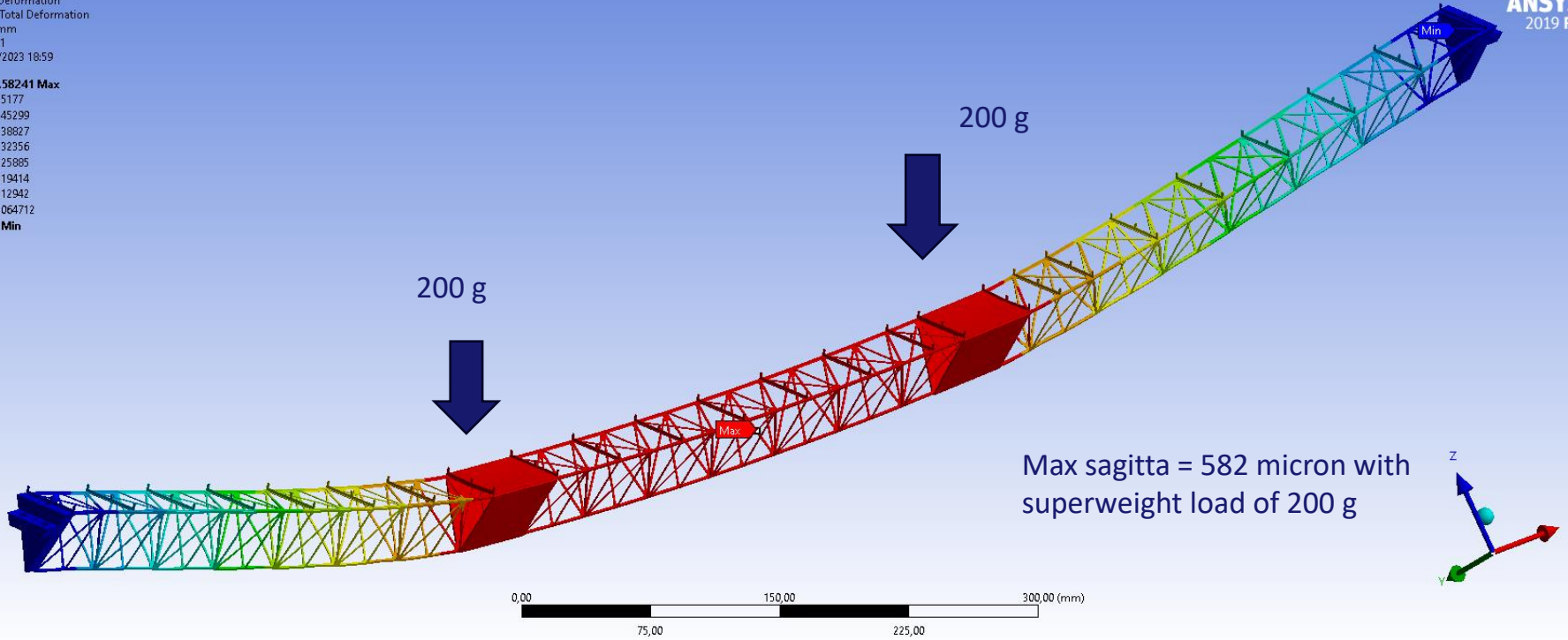
Real Weight Test

- Uniformly load distributed of 164,85 g
- Sagitta at 450 mm from the edge =210 micron
- Sagitta at the center of the structure = 280 micron

Copy of Copy of Static Structural
Total Deformation
Unit: mm
Scale: 1
6/2023 18:59

0,58241 Max
0,5177
0,45299
0,38627
0,32356
0,25885
0,19414
0,12942
0,064712
0 Min

ANSYS
2019 R



Result Data

Time [s]	Minimum [mm]	Maximum [mm]	Average [mm]
0	0	0,58241	0,40668

E: Copy of Copy of Static Structural

Total Deformation

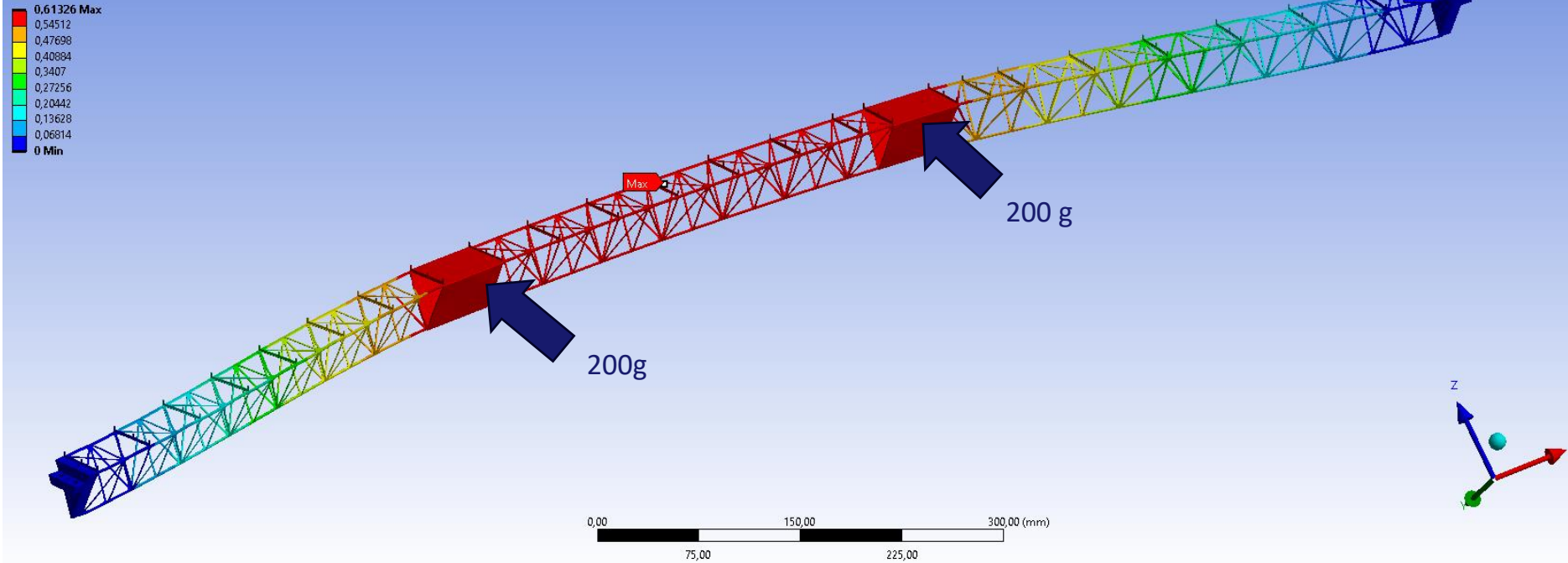
Type: Total Deformation

Units: mm

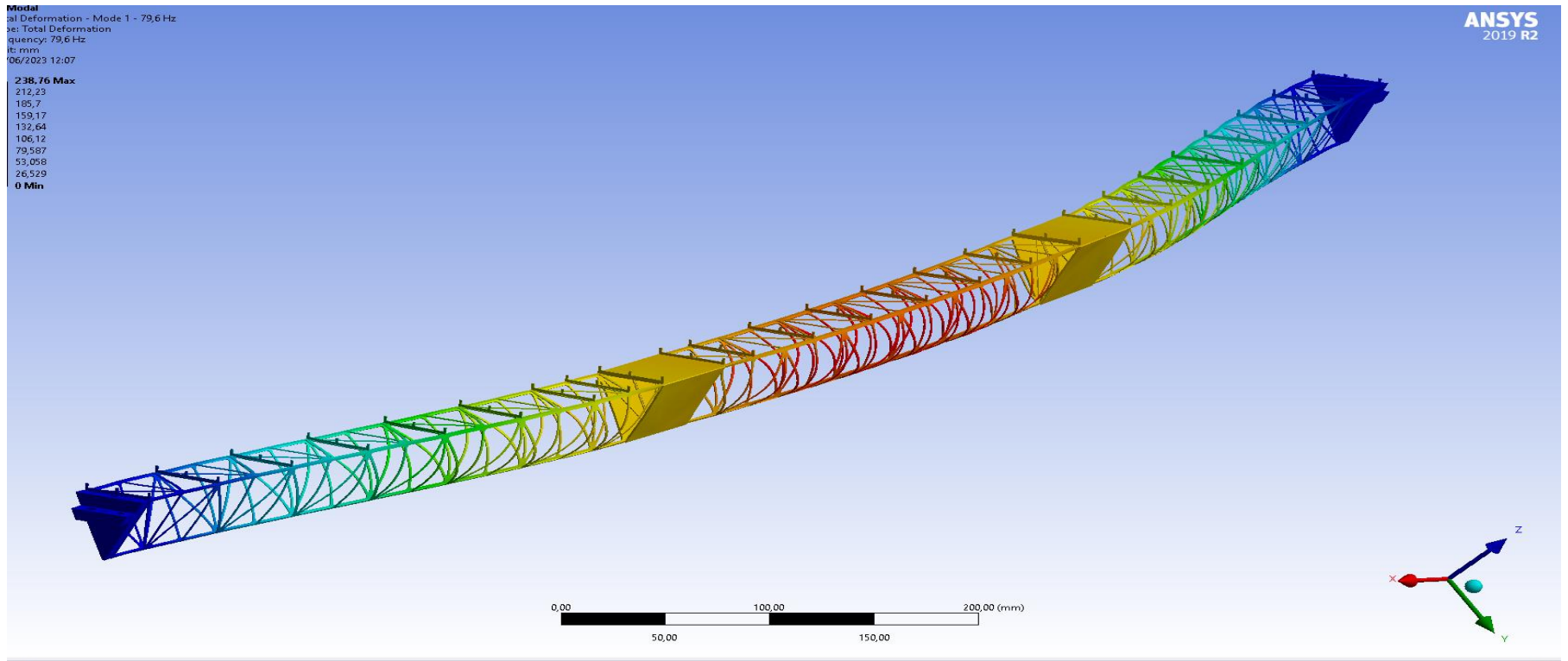
Time: 1

24/06/2023 22:39

ANSYS
2019 R

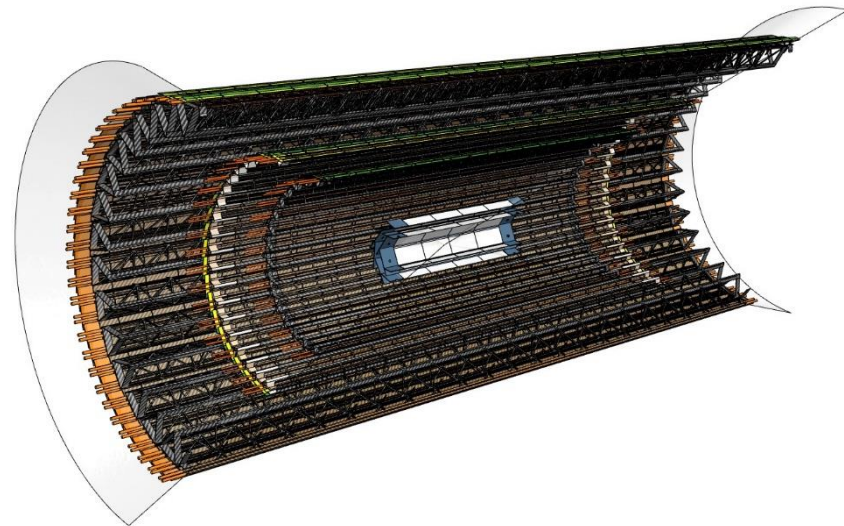


- First Frequency of resonance = 79,6 Hz
- Second frequency of resonance = 81,4 Hz
- Third Frequency of resonance = 166,6 Hz

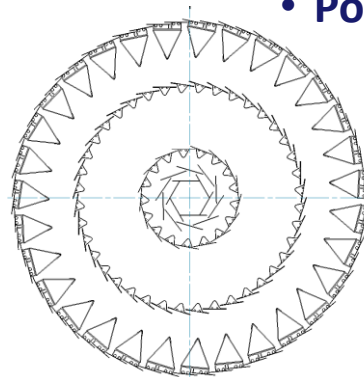


The SuperKEKB collider is planning a major upgrade of the I.R. to reach the design luminosity.

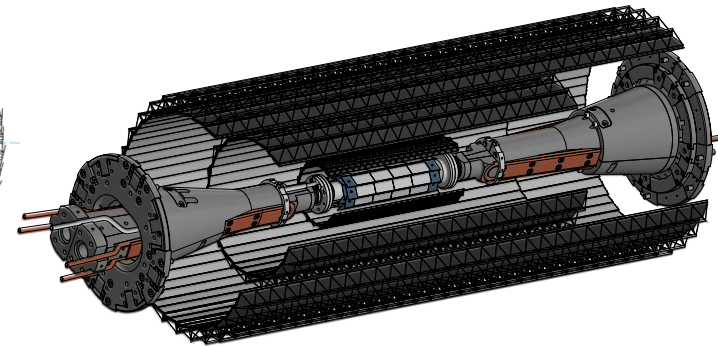
- **All-layer monolithic** vertex detector upgrade (**VTX**) to be installed in LS2 in ~2028:
 - More performant and resilient against higher machine backgrounds
 - Defined target spec's in terms of material budget, spatial resolution and integration time window
 - Baseline chip technology TJ180 nm, evolving from TJ-Monopix2:
 - **OBELIX**: First steps towards a Belle II CMOS sensor, **submission in 2024**
- Realization of prototypes of inner/outer layers ongoing, submitted to the mechanical, thermal and electrical characterization.
- In the finalization phase the CDR of the Belle II Upgrade.



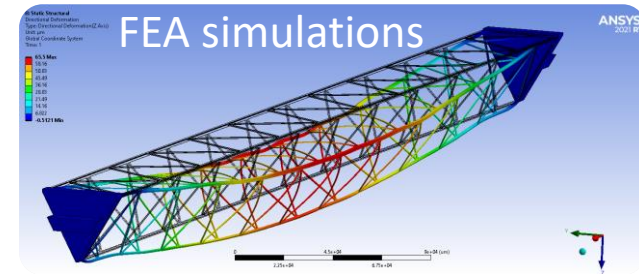
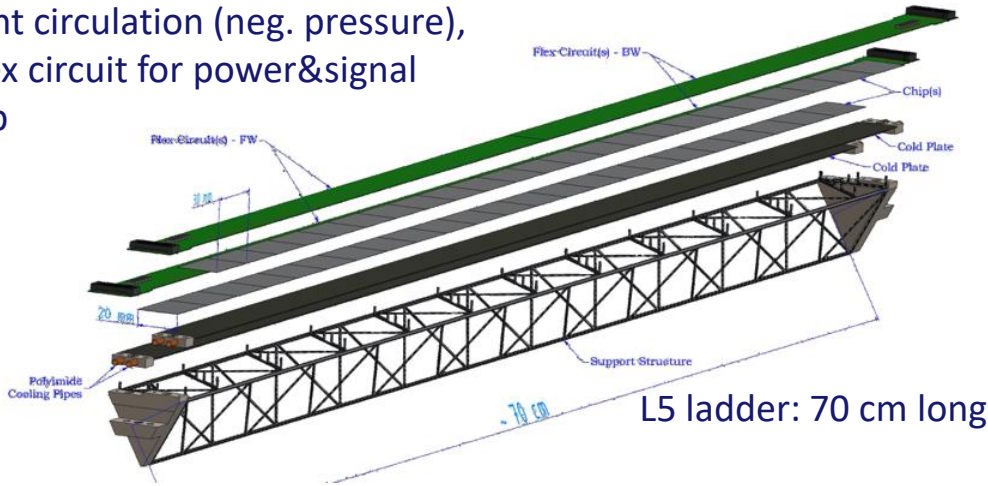
- **Low material budget** ($\sim 50 \mu\text{m}$ thin sensors):
0.1% X_0 (L1-2), 0.3-0.5% X_0 (L3-4), 0.8% X_0 (L5)
- **Requirements:**
 - Radiation levels for L1 ($r=1.4 \text{ cm}$)
 - TID: $\sim 100 \text{ Mrad}$
 - NIEL: $\sim 5 \cdot 10^{14} \text{ n}_{\text{eq}}/\text{cm}^2$
 - Hit-rate up to $120 \text{ MHz}/\text{cm}^2$
 - Resolution $< 15 \mu\text{m}$
 - Fast integration time 50-100 ns
 - Operation simplicity and reduced services
- **Depleted monolithic active CMOS pixel sensors**
 - Chip size: $2 \times 3 \text{ cm}^2$
 - Moderate pixel pitch $33 \mu\text{m}^2$
- 5 straight **fully pixelated** barrel layers
- **Same sensor chip for all layers**
- **iVTX:** Inner 2 layers
see Marcel Vos' talk
- **oVTX:** Outer sections (3 layers),
CF structure, water cooled
 - L3@3.9 cm (alternative @6.9 cm)
 - L4@90 cm, L5@13.5 cm
- **Power dissipation** $\sim 200 \text{ mW}/\text{cm}^2$



Outer VTX



Ladder structure design inspired by ALICE ITS2, composed of:
 CF support structure (truss), cold-plate with pipes for liquid coolant circulation (neg. pressure),
 Chip and Flex circuit for power&signal glued on top

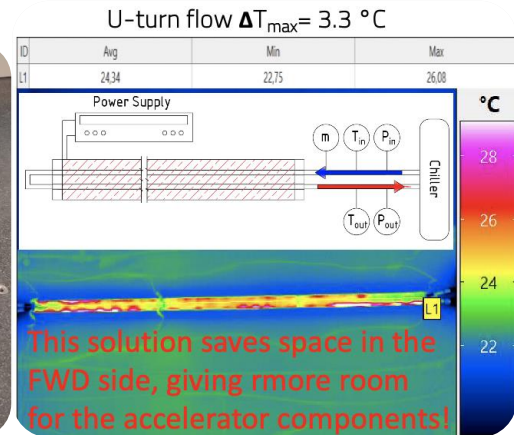
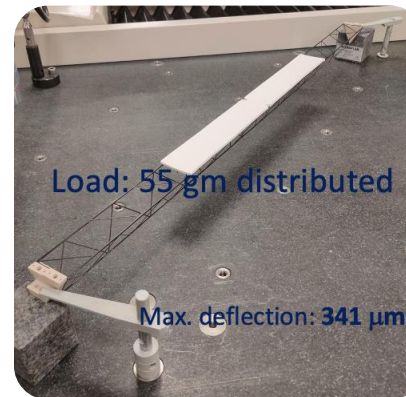


Performed mechanical characterization of the L5 prototype:

- Distortion: measurements of sagitta ($\sim 340 \mu\text{m}$)
- Vibration: 1st resonance frequency $\sim 250 \text{ Hz}$ (\gg earthquake f.)

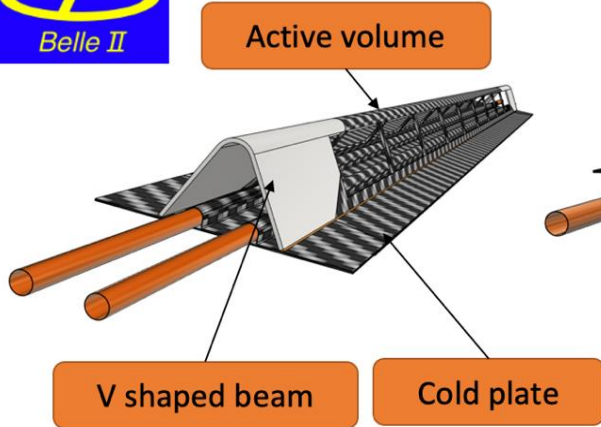
Thermal characterization:

- Used Kapton heaters, inlet ($T=10^\circ\text{C}$) and outlet on one side
- Uniform temperature along the ladder $\Delta T_{\text{max}}=3.3^\circ\text{C}$



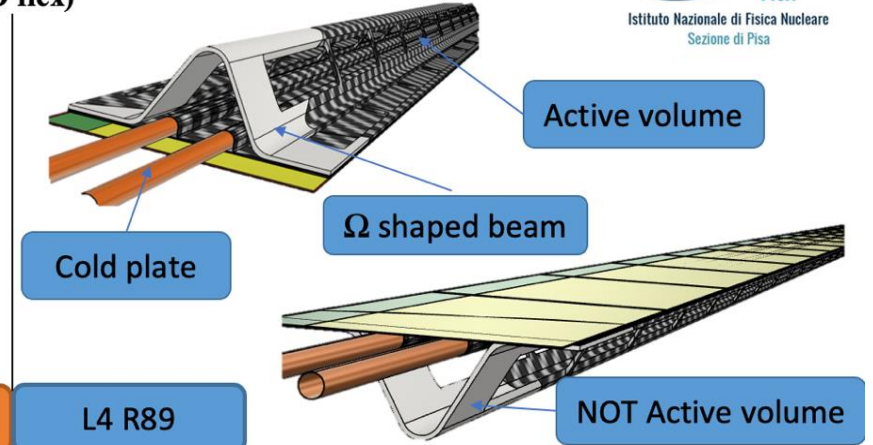
Ladders geometry

(with chips but NO flex)



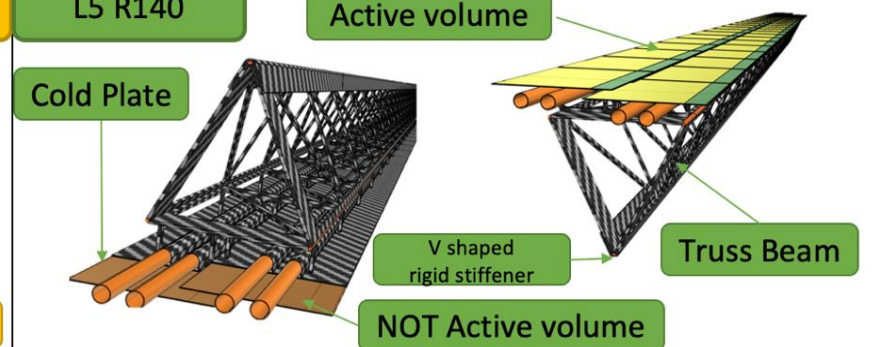
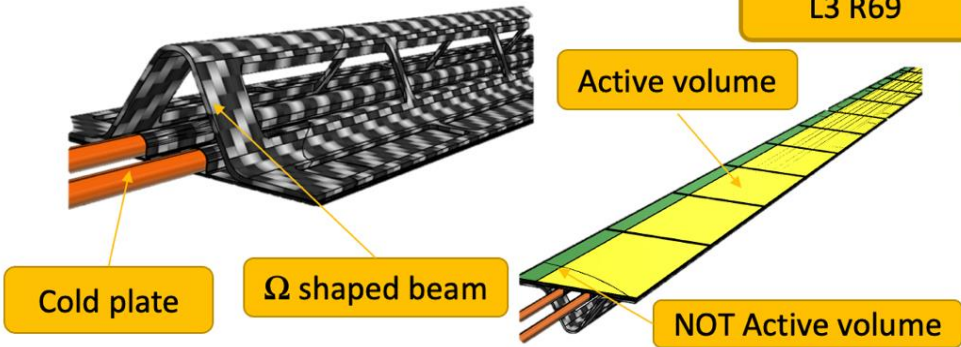
L3 R39

L3 R69



L4 R89

L5 R140



Thanks for the attention